

## Claims

We claim:

- 5 1. A semiconductor package comprising:
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- 10 a package substrate having a first surface;
- an integrated circuit electrically coupled to the first surface of the package substrate, the  
integrated circuit and the package substrate together forming the semiconductor  
package; and
- 15 a first inductance circuit formed within the semiconductor package; and
- a second inductance circuit formed within the semiconductor package,
- wherein the first inductance circuit is coupled in parallel to the second inductance circuit,  
and
- 20 wherein the first and second inductance circuits have substantially symmetrical geometric  
characteristics.

2. A semiconductor package comprising:

a package substrate having a first surface;

5 an integrated circuit electrically connected to said first surface of said package substrate,  
said integrated circuit and said package substrate together forming said  
semiconductor package, the integrated circuit and package substrate including  
frequency synthesizer circuitry; and

10 at least one inductance circuit formed entirely within said semiconductor package and  
formed at least partially between said integrated circuit and said package  
substrate, the inductance circuit at least in part determining an output frequency  
for the frequency synthesizer circuitry;

15 wherein said frequency synthesizer circuitry has an output frequency selectably operable  
within a plurality of bands, and wherein said at least one inductance circuit forms  
part of a controlled oscillator circuit within said frequency synthesizer circuitry,  
the output frequency being dependent upon the controlled oscillator circuit.

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